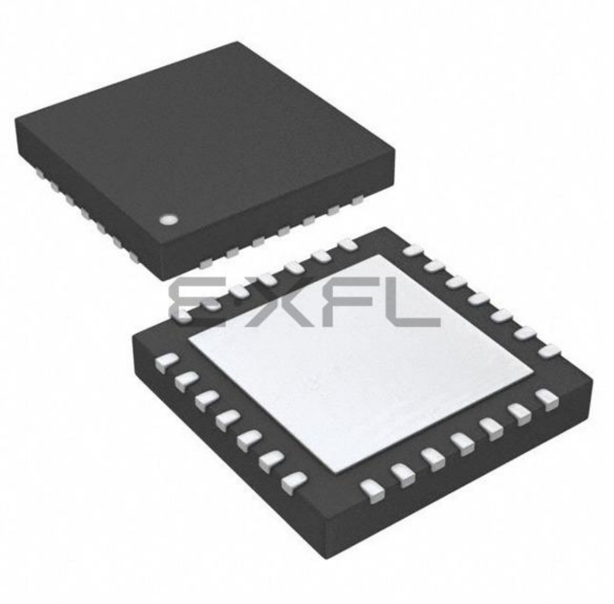

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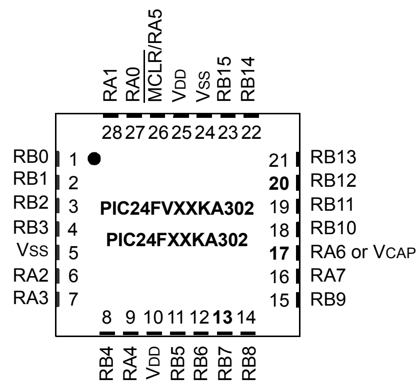
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	23
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fv16ka302t-i-ml

Pin Diagrams

28-Pin QFN(1,2,3)



Pin	Pin Features	
	PIC24FVXXKA302	**PIC24FXXKA302**
1	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0	PGED1/AN2/ULPWU/CTCMP/C1IND/C2INB/C3IND/U2TX/CN4/RB0
2	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1	PGEC1/AN3/C1INC/C2INA/U2RX/CTED12/CN5/RB1
3	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/U1RX/CTED13/CN6/RB2	AN4/C1INB/C2IND/SDA2/T5CK/T4CK/U1RX/CTED13/CN6/RB2
4	AN5/C1INA/C2INC/SCL2/CN7/RB3	AN5/C1INA/C2INC/SCL2/CN7/RB3
5	VSS	VSS
6	OSCI/AN13/CLKI/CN30/RA2	OSCI/AN13/CLKI/CN30/RA2
7	OSCO/AN14/CLKO/CN29/RA3	OSCO/AN14/CLKO/CN29/RA3
8	SOSCI/AN15/$\overline{\text{U2RTS}}$/CN1/RB4	SOSCI/AN15/$\overline{\text{U2RTS}}$/CN1/RB4
9	SOSCO/SCLKI/$\overline{\text{U2CTS}}$/CN0/RA4	SOSCO/SCLKI/$\overline{\text{U2CTS}}$/CN0/RA4
10	VDD	VDD
11	PGED3/ASDA1(2)/SCK2/CN27/RB5	PGED3/ASDA1(2)/SCK2/CN27/RB5
12	PGEC3/ASCL1(2)/SDO2/CN24/RB6	PGEC3/ASCL1(2)/SDO2/CN24/RB6
13	**U1TX/C2OUT/OC1/INT0/CN23/RB7**	**U1TX/INT0/CN23/RB7**
14	SCL1/$\overline{\text{U1CTS}}$/C3OUT/CTED10/CN22/RB8	SCL1/$\overline{\text{U1CTS}}$/C3OUT/CTED10/CN22/RB8
15	SDA1/T1CK/$\overline{\text{U1RTS}}$/IC2/CTED4/CN21/RB9	SDA1/T1CK/$\overline{\text{U1RTS}}$/IC2/CTED4/CN21/RB9
16	SDI2/IC1/CTED3/CN9/RA7	SDI2/IC1/CTED3/CN9/RA7
17	**VCAP**	**C2OUT/OC1/CTED1/INT2/CN8/RA6**
18	PGED2/SDI1/OC3/CTED11/CN16/RB10	PGED2/SDI1/OC3/CTED11/CN16/RB10
19	PGEC2/SCK1/OC2/CTED9/CN15/RB11	PGEC2/SCK1/OC2/CTED9/CN15/RB11
20	**AN12/HLVDIN/$\overline{\text{SS2}}$/IC3/CTED2/INT2/CN14/RB12**	**AN12/HLVDIN/$\overline{\text{SS2}}$/IC3/CTED2/CN14/RB12**
21	AN11/SDO1/OCFB/CTPLS/CN13/RB13	AN11/SDO1/OCFB/CTPLS/CN13/RB13
22	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/**INT1**/CN12/RB14	CVREF/AN10/C3INB/RTCC/C1OUT/OCFA/CTED5/**INT1**/CN12/RB14
23	AN9/C3INA/T3CK/T2CK/REFO/$\overline{\text{SS1}}$/CTED6/CN11/RB15	AN9/C3INA/T3CK/T2CK/REFO/$\overline{\text{SS1}}$/CTED6/CN11/RB15
24	VSS/AVSS	VSS/AVSS
25	VDD/AVDD	VDD/AVDD
26	$\overline{\text{MCLR}}$/VPP/RA5	$\overline{\text{MCLR}}$/VPP/RA5
27	VREF+/CVREF+/AN0/C3INC/CTED1/CN2/RA0	VREF+/CVREF+/AN0/C3INC/CN2/RA0
28	CVREF-/VREF-/AN1/CN3/RA1	CVREF-/VREF-/AN1/CN3/RA1

Legend: Pin numbers in **bold** indicate pin function differences between PIC24FV and PIC24F devices.

Note 1: Exposed pad on underside of device is connected to VSS.

2: Alternative multiplexing for SDA1 (ASDA1) and SCL1 (ASCL1) when the I2CSEL Configuration bit is set.

3: PIC24F32KA304 device pins have a maximum voltage of 3.6V and are not 5V tolerant.

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FIGURE 8-1: PIC24F INTERRUPT VECTOR TABLE

Decreasing Natural Order Priority

Reset – `GOTO` Instruction	000000h
Reset – `GOTO` Address	000002h
Reserved	000004h
Oscillator Fail Trap Vector	
Address Error Trap Vector	
Stack Error Trap Vector	
Math Error Trap Vector	
Reserved	
Reserved	
Reserved	
Interrupt Vector 0	000014h
Interrupt Vector 1	
—	
—	
—	
Interrupt Vector 52	00007Ch
Interrupt Vector 53	00007Eh
Interrupt Vector 54	000080h
—	
—	
—	
Interrupt Vector 116	0000FCh
Interrupt Vector 117	0000FEh
Reserved	000100h
Reserved	000102h
Reserved	
Oscillator Fail Trap Vector	
Address Error Trap Vector	
Stack Error Trap Vector	
Math Error Trap Vector	
Reserved	
Reserved	
Reserved	
Interrupt Vector 0	000114h
Interrupt Vector 1	
—	
—	
—	
Interrupt Vector 52	00017Ch
Interrupt Vector 53	00017Eh
Interrupt Vector 54	000180h
—	
—	
—	
Interrupt Vector 116	
Interrupt Vector 117	0001FEh
Start of Code	000200h

Interrupt Vector Table (IVT)(1)

Alternate Interrupt Vector Table (AIVT)(1)

Note 1: See Table 8-2 for the interrupt vector list.

REGISTER 8-16: IEC5: INTERRUPT ENABLE CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **ULPWUIE:** Ultra Low-Power Wake-up Interrupt Enable Bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

REGISTER 8-19: IPC2: INTERRUPT PRIORITY CONTROL REGISTER 2

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U1RXIP2	U1RXIP1	U1RXIP0	—	SPI1IP2	SPI1IP1	SPI1IP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SPF1IP2	SPF1IP1	SPF1IP0	—	T3IP2	T3IP1	T3IP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U1RXIP<2:0>:** UART1 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **SPI1IP<2:0>:** SPI1 Event Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **SPF1IP<2:0>:** SPI1 Fault Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **T3IP<2:0>:** Timer3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

10.2.4.2 Exiting Deep Sleep Mode

Deep Sleep mode exits on any one of the following events:

- A POR event on V_{DD} supply. If there is no DSBOR circuit to re-arm the V_{DD} supply POR circuit, the external V_{DD} supply must be lowered to the natural arming voltage of the POR circuit.
- A DSWDT time-out. When the DSWDT timer times out, the device exits Deep Sleep.
- An RTCC alarm (if RTCEN = `1`).
- An assertion (‘`0`’) of the $\overline{\text{MCLR}}$ pin.
- An assertion of the INT0 pin (if the interrupt was enabled before Deep Sleep mode was entered). The polarity configuration is used to determine the assertion level (‘`0`’ or ‘`1`’) of the pin that will cause an exit from Deep Sleep mode. Exiting from Deep Sleep mode requires a change on the INT0 pin while in Deep Sleep mode.

Note:	Any interrupt pending when entering Deep Sleep mode is cleared.

Exiting Deep Sleep mode generally does not retain the state of the device and is equivalent to a Power-on Reset (POR) of the device. Exceptions to this include the RTCC (if present), which remains operational through the wake-up, the DSGPRx registers and DSWDT.

Wake-up events that occur after Deep Sleep exits, but before the POR sequence completes, are ignored and are not be captured in the DSWAKE register.

The sequence for exiting Deep Sleep mode is:

1. After a wake-up event, the device exits Deep Sleep and performs a POR. The DSEN bit is cleared automatically. Code execution resumes at the Reset vector.
2. To determine if the device exited Deep Sleep, read the Deep Sleep bit, DPSLP (RCON<10>). This bit will be set if there was an exit from Deep Sleep mode; if the bit is set, clear it.
3. Determine the wake-up source by reading the DSWAKE register.
4. Determine if a DSBOR event occurred during Deep Sleep mode by reading the DSBOR bit (DSCON<1>).
5. If application context data has been saved, read it back from the DSGPR0 and DSGPR1 registers.
6. Clear the RELEASE bit (DSCON<0>).

10.2.4.3 Saving Context Data with the DSGPR0/DSGPR1 Registers

As exiting Deep Sleep mode causes a POR, most Special Function Registers reset to their default POR values. In addition, because V_{CORE} power is not supplied in Deep Sleep mode, information in data RAM may be lost when exiting this mode.

Applications which require critical data to be saved prior to Deep Sleep may use the Deep Sleep General Purpose registers, DSGPR0 and DSGPR1 or data EEPROM (if available). Unlike other SFRs, the contents of these registers are preserved while the device is in Deep Sleep mode. After exiting Deep Sleep, software can restore the data by reading the registers and clearing the RELEASE bit (DSCON<0>).

10.2.4.4 I/O Pins During Deep Sleep

During Deep Sleep, the general purpose I/O pins retain their previous states and the Secondary Oscillator (SOSC) will remain running, if enabled. Pins that are configured as inputs (TRISx bit is set), prior to entry into Deep Sleep, remain high-impedance during Deep Sleep. Pins that are configured as outputs (TRISx bit is clear), prior to entry into Deep Sleep, remain as output pins during Deep Sleep. While in this mode, they continue to drive the output level determined by their corresponding LATx bit at the time of entry into Deep Sleep.

Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance and pins configured as outputs continue to drive their previous value. After waking up, the TRIS and LAT registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/O will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>), the I/O pins are “released”. This causes the I/O pins to take the states configured by their respective TRISx and LATx bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released, similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

If a $\overline{\text{MCLR}}$ Reset event occurs during Deep Sleep, the DSGPRx, DSCON and DSWAKE registers will remain valid, and the RELEASE bit will remain set. The state of the SOSC will also be retained. The I/O pins, however, will be reset to their $\overline{\text{MCLR}}$ Reset state. Since RELEASE is still set, changes to the SOSCEN bit (OSCCON<1>) cannot take effect until the RELEASE bit is cleared.

In all other Deep Sleep wake-up cases, application firmware must clear the RELEASE bit in order to reconfigure the I/O pins.

16.0 SERIAL PERIPHERAL INTERFACE (SPI)

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Serial Peripheral Interface, refer to the *“PIC24F Family Reference Manual”*, **Section 23. “Serial Peripheral Interface (SPI)”** (DS39699).

The Serial Peripheral Interface (SPI) module is a synchronous serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial data EEPROMs, shift registers, display drivers, A/D Converters, etc. The SPI module is compatible with Motorola® SPI and SIOP interfaces.

The module supports operation in two buffer modes. In Standard mode, data is shifted through a single serial buffer. In Enhanced Buffer mode, data is shifted through an 8-level FIFO buffer.

> **Note:** Do not perform read-modify-write operations (such as bit-oriented instructions) on the SPI1BUF register in either Standard or Enhanced Buffer mode.

The module also supports a basic framed SPI protocol while operating in either Master or Slave mode. A total of four framed SPI configurations are supported.

The SPI serial interface consists of four pins:

- SDI1: Serial Data Input
- SDO1: Serial Data Output
- SCK1: Shift Clock Input or Output
- $\overline{\text{SS1}}$: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPI module can be configured to operate using 2, 3 or 4 pins. In the 3-pin mode, $\overline{\text{SS1}}$ is not used. In the 2-pin mode, both SDO1 and $\overline{\text{SS1}}$ are not used.

Block diagrams of the module, in Standard and Enhanced Buffer modes, are shown in Figure 16-1 and Figure 16-2.

The devices of the PIC24FV32KA304 family offer two SPI modules on a device.

> **Note:** In this section, the SPI modules are referred to as SPIx. Special Function Registers (SFRs) will follow a similar notation. For example, SPI1CON1 or SPI1CON2 refers to the control register for the SPI1 module.

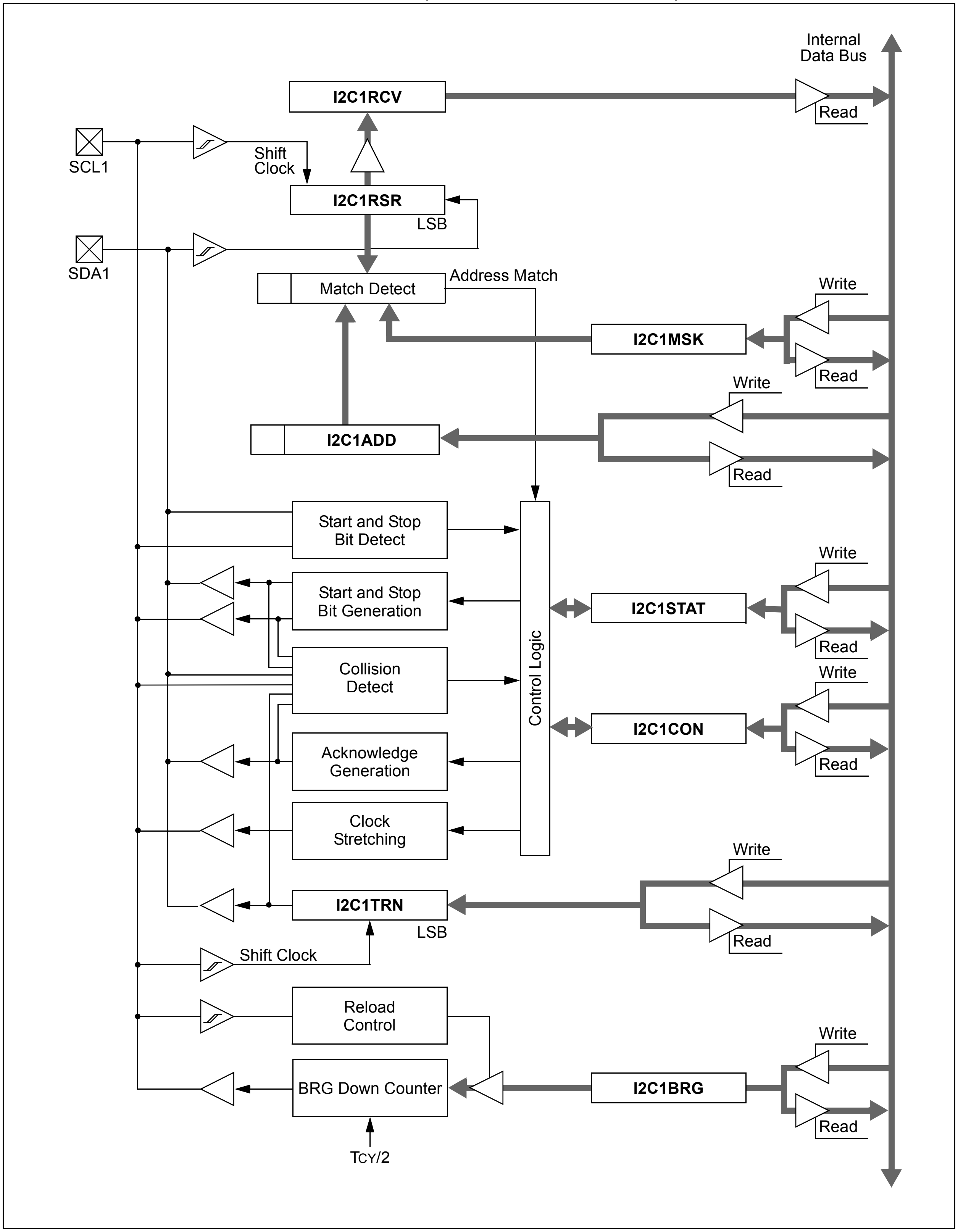
To set up the SPI1 module for the Standard Master mode of operation:

1. If using interrupts:
   a) Clear the SPI1IF bit in the IFS0 register.
   b) Set the SPI1IE bit in the IEC0 register.
   c) Write the respective SPI1IPx bits in the IPC2 register to set the interrupt priority.
2. Write the desired settings to the SPI1CON1 and SPI1CON2 registers with the MSTEN bit (SPI1CON1<5>) = `1`.
3. Clear the SPIROV bit (SPI1STAT<6>).
4. Enable SPI operation by setting the SPIEN bit (SPI1STAT<15>).
5. Write the data to be transmitted to the SPI1BUF register. Transmission (and reception) will start as soon as data is written to the SPI1BUF register.

To set up the SPI1 module for the Standard Slave mode of operation:

1. Clear the SPI1BUF register.
2. If using interrupts:
   a) Clear the SPI1IF bit in the IFS0 register.
   b) Set the SPI1IE bit in the IEC0 register.
   c) Write the respective SPI1IPx bits in the IPC2 register to set the interrupt priority.
3. Write the desired settings to the SPI1CON1 and SPI1CON2 registers with the MSTEN bit (SPI1CON1<5>) = `0`.
4. Clear the SMP bit.
5. If the CKE bit is set, then the SSEN bit (SPI1CON1<7>) must be set to enable the $\overline{\text{SS1}}$ pin.
6. Clear the SPIROV bit (SPI1STAT<6>).
7. Enable SPI operation by setting the SPIEN bit (SPI1STAT<15>).

FIGURE 17-1: I²C™ BLOCK DIAGRAM (I2C1 MODULE IS SHOWN)



REGISTER 20-1: CRCCON1: CRC CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R-0	R-0	R-0	R-0	R-0
CRCEN	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0
bit 15							bit 8

R-0, HSC	R-1, HSC	R/W-0	R/W-0, HC	R/W-0	U-0	U-0	U-0
CRCFUL	CRCMPT	CRCISEL	CRCGO	LENDIAN	—	—	—
bit 7							bit 0

Legend:	HC = Hardware Clearable bit	HSC = Hardware Settable/Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CRCEN**: CRC Enable bit
1 = Module is enabled
0 = Module is enabled
All state machines, pointers and CRCWDAT/CRCDAT registers are reset; other SFRs are NOT reset.

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CSIDL:** CRC Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12-8 **VWORD<4:0>:** Pointer Value bits
Indicates the number of valid words in the FIFO, which has a maximum value of 8 when PLEN<4:0> > 7 or 16 when PLEN<4:0> ≤ 7.

bit 7 **CRCFUL**: CRC FIFO Full bit
1 = FIFO is full
0 = FIFO is not full

bit 6 **CRCMPT:** CRC FIFO Empty Bit
1 = FIFO is empty
0 = FIFO is not empty

bit 5 **CRCISEL:** CRC interrupt Selection bit
1 = Interrupt on FIFO is empty; CRC calculation is not complete
0 = Interrupt on shift is complete and CRCWDAT result is ready

bit 4 **CRCGO:** Start CRC bit
1 = Starts CRC serial shifter
0 = CRC serial shifter is turned off

bit 3 **LENDIAN:** Data Shift Direction Select bit
1 = Data word is shifted into the CRC, starting with the LSb (little endian)
0 = Data word is shifted into the CRC, starting with the MSb (big endian)

bit 2-0 **Unimplemented:** Read as ‘0’

21.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

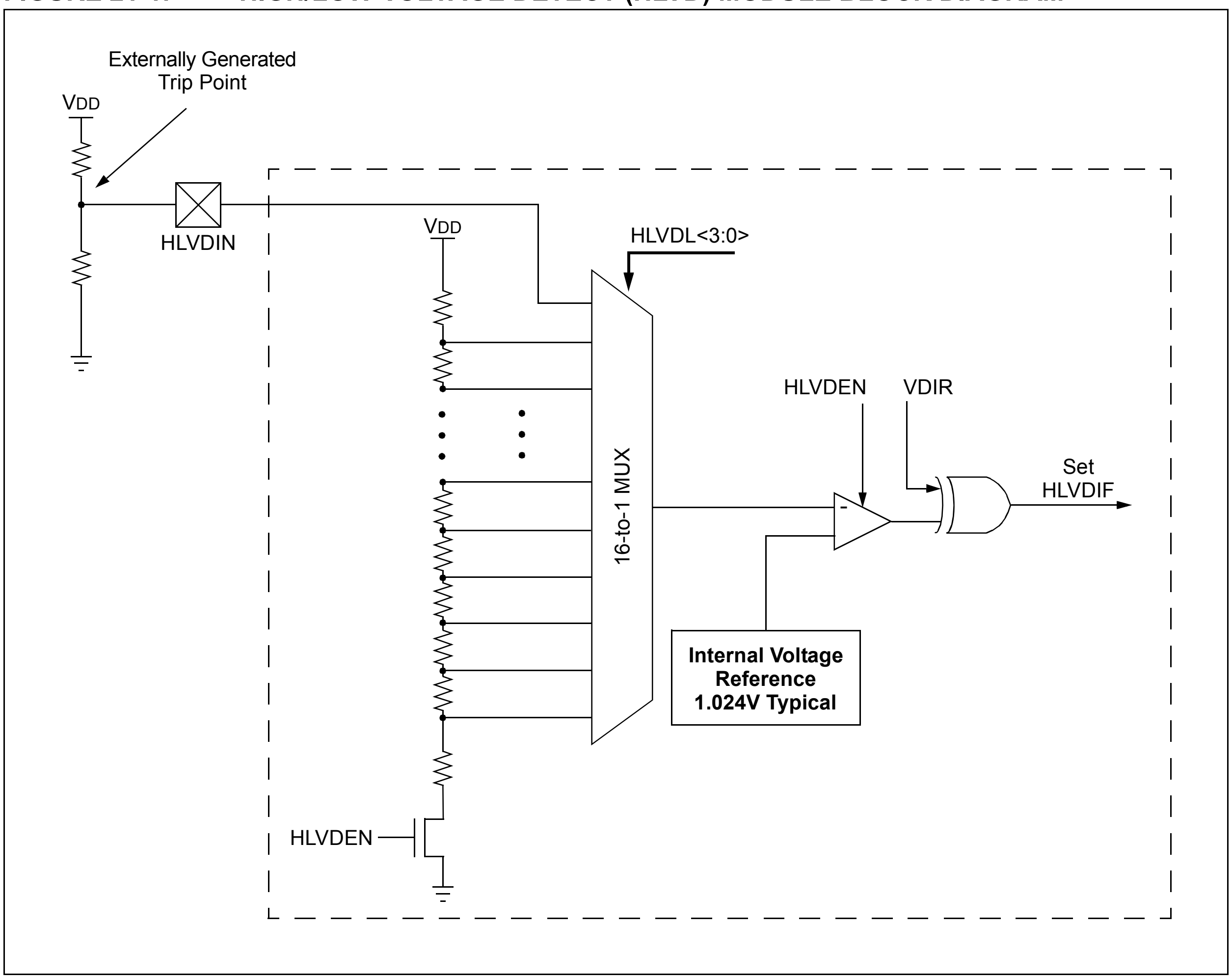
Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the High/Low-Voltage Detect, refer to the *"PIC24F Family Reference Manual"*, **Section 36. "High-Level Integration with Programmable High/Low-Voltage Detect (HLVD)"** (DS39725).

The High/Low-Voltage Detect module (HLVD) is a programmable circuit that allows the user to specify both the device voltage trip point and the direction of change.

An interrupt flag is set if the device experiences an excursion past the trip point in the direction of change. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The HLVD Control register (see Register 21-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

FIGURE 21-1: HIGH/LOW-VOLTAGE DETECT (HLVD) MODULE BLOCK DIAGRAM



NOTES:

REGISTER 26-2: FGS: GENERAL SEGMENT CONFIGURATION REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/C-1	R/C-1
—	—	—	—	—	—	GSS0	GWRP
bit 7							bit 0

Legend:			
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **GSS0:** General Segment Code Flash Code Protection bit
1 = No protection
0 = Standard security is enabled

bit 0 **GWRP:** General Segment Code Flash Write Protection bit
1 = General segment may be written
0 = General segment is write-protected

REGISTER 26-3: FOSCSEL: OSCILLATOR SELECTION CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	U-0	U-0	R/P-1	R/P-1	R/P-1
IESO	LPRCSEL	SOSCSRC	—	—	FNOSC2	FNOSC1	FNOSC0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IESO:** Internal External Switchover bit
1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **LPRCSEL:** Internal LPRC Oscillator Power Select bit
1 = High-Power/High-Accuracy mode
0 = Low-Power/Low-Accuracy mode

bit 5 **SOSCSRC:** Secondary Oscillator Clock Source Configuration bit
1 = SOSC analog crystal function is available on the SOSCI/SOSCO pins
0 = SOSC crystal is disabled; digital SCLKI function is selected on the SOSCO pin

bit 4-3 **Unimplemented:** Read as '0'

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits
000 = Fast RC Oscillator (FRC)
001 = Fast RC Oscillator with Divide-by-N with PLL module (FRCDIV+PLL)
010 = Primary Oscillator (XT, HS, EC)
011 = Primary Oscillator with PLL module (HS+PLL, EC+PLL)
100 = Secondary Oscillator (SOSC)
101 = Low-Power RC Oscillator (LPRC)
110 = 500 kHz Low-Power FRC Oscillator with Divide-by-N (LPFRCDIV)
111 = 8 MHz FRC Oscillator with Divide-by-N (FRCDIV)

27.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit™ 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows® programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit™ 2 enables in-circuit debugging on most PIC® microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

27.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

27.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta A/D, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

28.0 INSTRUCTION SET SUMMARY

Note:	This chapter is a brief summary of the PIC24F instruction set architecture and is not intended to be a comprehensive reference source.

The PIC24F instruction set adds many enhancements to the previous PIC® MCU instruction sets, while maintaining an easy migration from previous PIC MCU instruction sets. Most instructions are a single program memory word. Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction. The instruction set is highly orthogonal and is grouped into four basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- Control operations

Table 28-1 lists the general symbols used in describing the instructions. The PIC24F instruction set summary in Table 28-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register ‘Wb’ without any address modifier
- The second source operand, which is typically a register ‘Ws’ with or without an address modifier
- The destination of the result, which is typically a register ‘Wd’ with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value, ‘f’
- The destination, which could either be the file register, ‘f’, or the W0 register, which is denoted as ‘WREG’

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of ‘Ws’ or ‘f’)
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register ‘Wb’)

The literal instructions that involve data movement may use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by the value of ‘k’)
- The W register or file register where the literal value is to be loaded (specified by ‘Wb’ or ‘f’)

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register ‘Wb’ without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register ‘Wd’ with or without an address modifier

The control instructions may use some of the following operands:

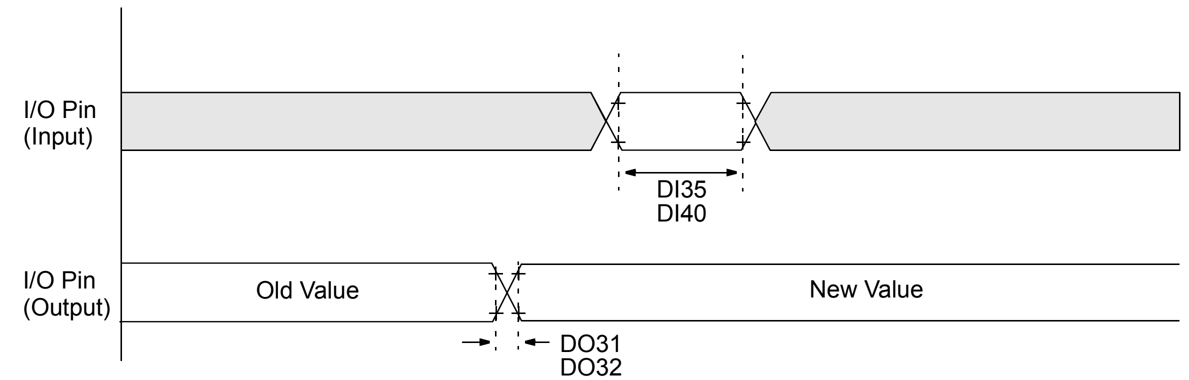
- A program memory address
- The mode of the table read and table write instructions

All instructions are a single word, except for certain double-word instructions, which were made double-word instructions so that all of the required information is available in these 48 bits. In the second word, the 8 MSbs are ‘0’s. If this second word is executed as an instruction (by itself), it will execute as a `NOP`.

Most single-word instructions are executed in a single instruction cycle, unless a conditional test is true or the Program Counter (PC) is changed as a result of the instruction. In these cases, the execution takes two instruction cycles, with the additional instruction cycle(s) executed as a `NOP`. Notable exceptions are the `BRA` (unconditional/computed branch), indirect `CALL/GOTO`, all table reads and writes, and `RETURN/RETFIE` instructions, which are single-word instructions but take two or three cycles.

Certain instructions that involve skipping over the subsequent instruction require either two or three cycles if the skip is performed, depending on whether the instruction being skipped is a single-word or two-word instruction. Moreover, double-word moves require two cycles. The double-word instructions execute in two instruction cycles.

FIGURE 29-5: CLKO AND I/O TIMING CHARACTERISTICS



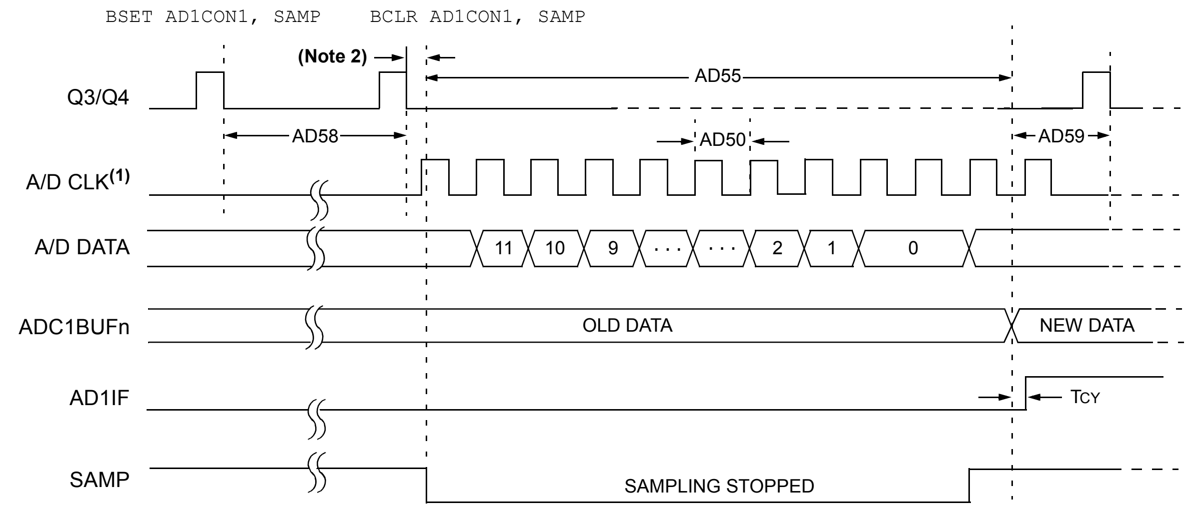
Note: Refer to Figure 29-3 for load conditions.

TABLE 29-23: CLKO AND I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx Pin High or Low Time (output)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in “Typ” column is at 3.3V, +25°C (PIC24F32KA3XX); 5.0V, +25°C (PIC24FV32KA3XX), unless otherwise stated.

FIGURE 29-22: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the `SLEEP` instruction to be executed.

2: This is a minimal RC delay (typically 100 ns) which also disconnects the holding capacitor from the analog input.

TABLE 29-41: A/D CONVERSION TIMING REQUIREMENTS(1)

AC CHARACTERISTICS			**Standard Operating Conditions:** 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	A/D Clock Period	600	—	—	ns	TCY = 75 ns, AD1CON3 in default state
AD51	TRC	A/D Internal RC Oscillator Period	—	1.67	—	μs	
Conversion Rate							
AD55	TCONV	Conversion Time	— —	12 14	— —	TAD TAD	10-bit results 12-bit results
AD56	FCNV	Throughput Rate	—	—	100	ksps	
AD57	TSAMP	Sample Time	—	1	—	TAD	
AD58	TACQ	Acquisition Time	750	—	—	ns	**(Note 2)**
AD59	TSWC	Switching Time from Convert to Sample	—	—	**(Note 3)**		
AD60	TDIS	Discharge Time	12	—	—	TAD	
Clock Parameters							
AD61	TPSS	Sample Start Delay from Setting Sample bit (SAMP)	2	—	3	TAD	

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: The time for the holding capacitor to acquire the “New” input voltage when the voltage changes full scale after the conversion (VDD to VSS or VSS to VDD).

3: On the following cycle of the device clock.

FIGURE 30-24: TYPICAL V_{OH} vs. I_{OH} (GENERAL PURPOSE I/O, AS A FUNCTION OF V_{DD})

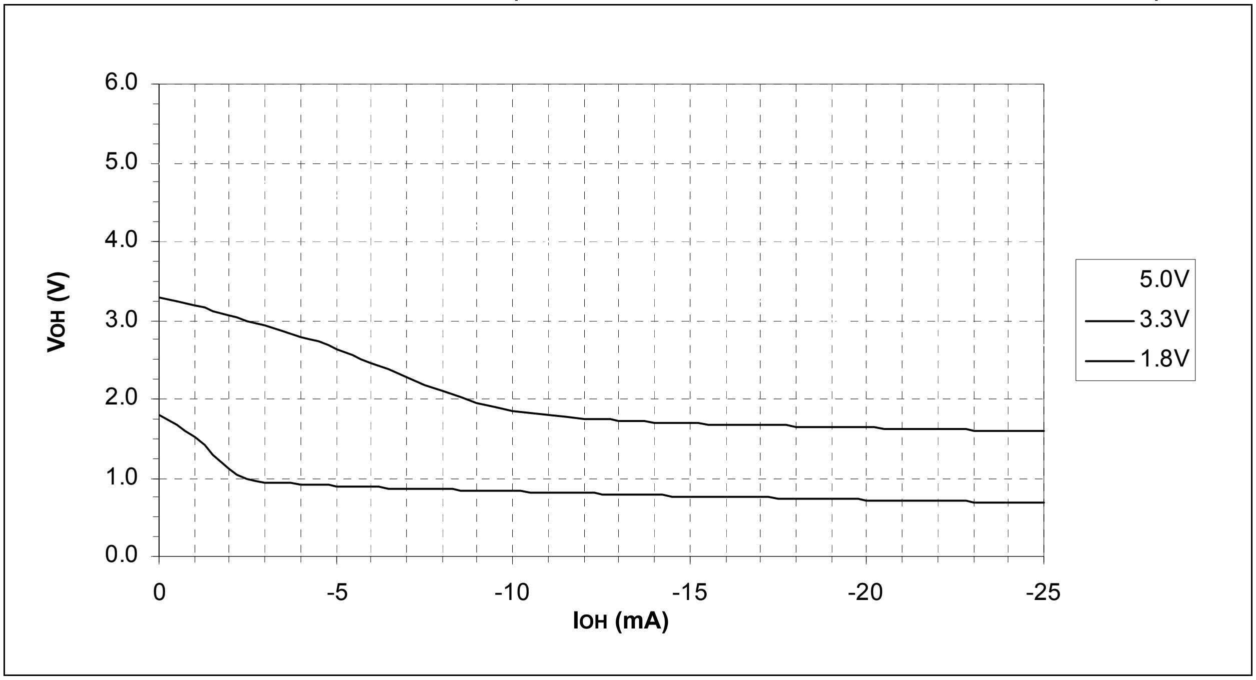
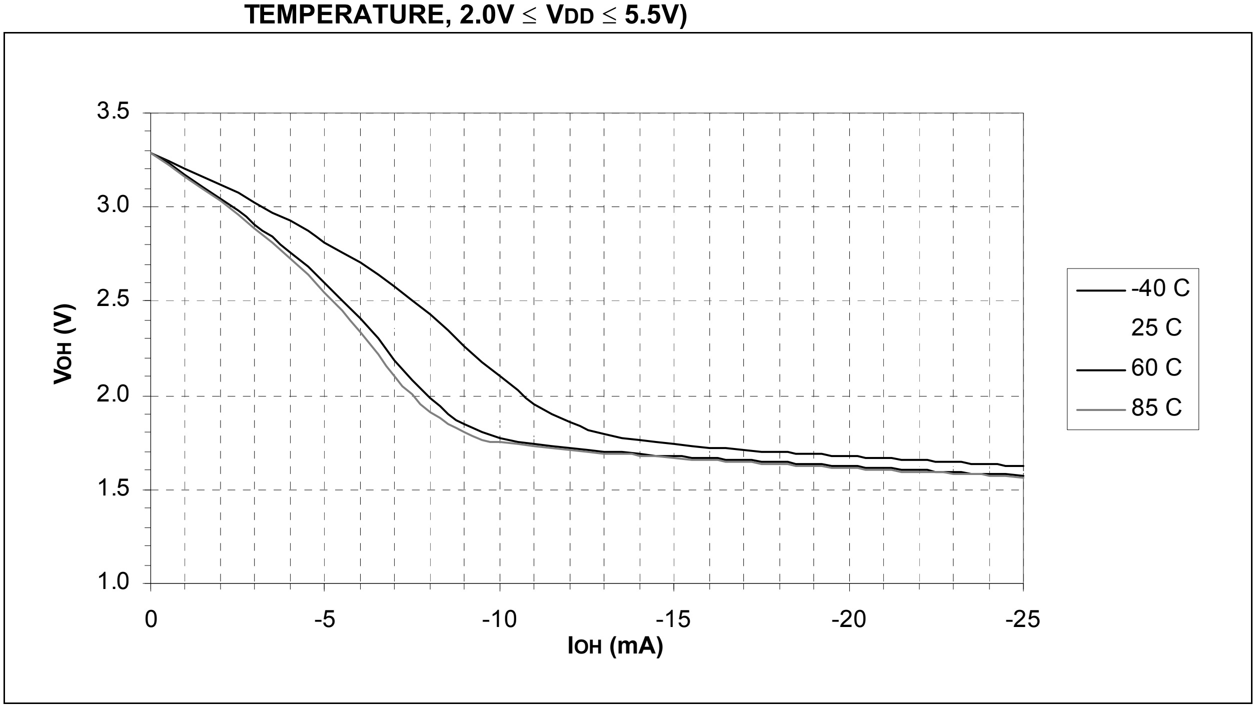
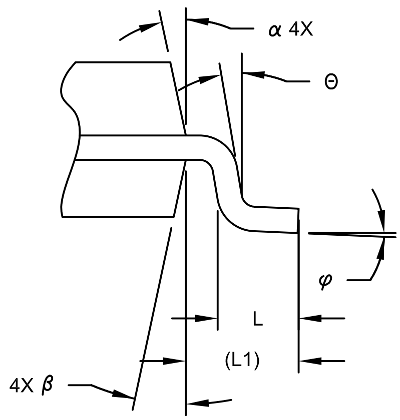


FIGURE 30-25: TYPICAL V_{OH} vs. I_{OH} (GENERAL PURPOSE I/O, AS A FUNCTION OF TEMPERATURE, 2.0V ≤ V_{DD} ≤ 5.5V)

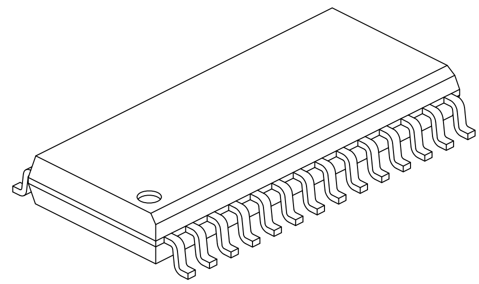


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E	10.30 BSC		
Molded Package Width	E1	7.50 BSC		
Overall Length	D	17.90 BSC		
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1	1.40 REF		
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

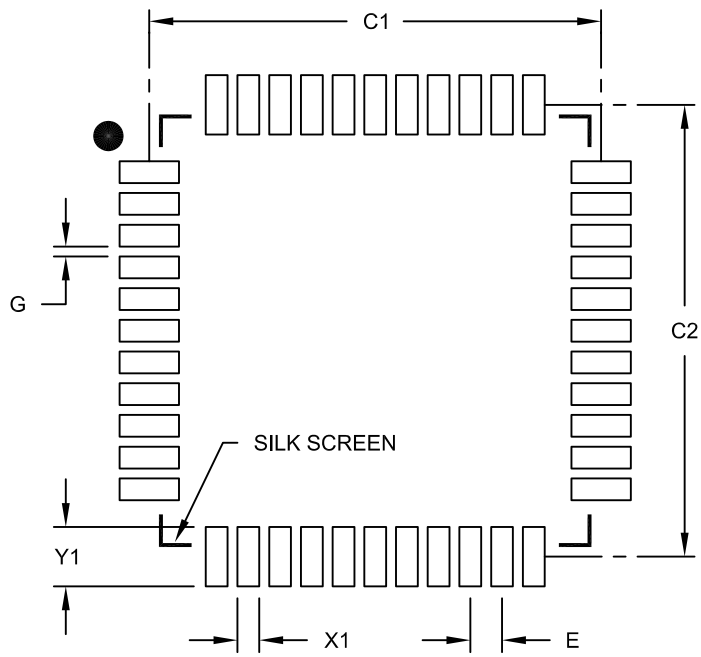
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

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Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.